

Hitachi Focused Ion & Electron Beam System  
nanoDUE' T NB5000

*Hitachi High-Technologies*

# NB5000

HITACHI

# *Focused Ion & Electron Beam Sys*

## **Hitachi's high performance FIB-SEM provides unparalleled nano-analyses of devices and functional materials !!**

Legendary Hitachi reliability and performance in an integrated system

(Ultra-high performance FIB and high resolution FE-SEM)

enabling high-throughput specimen preparation,

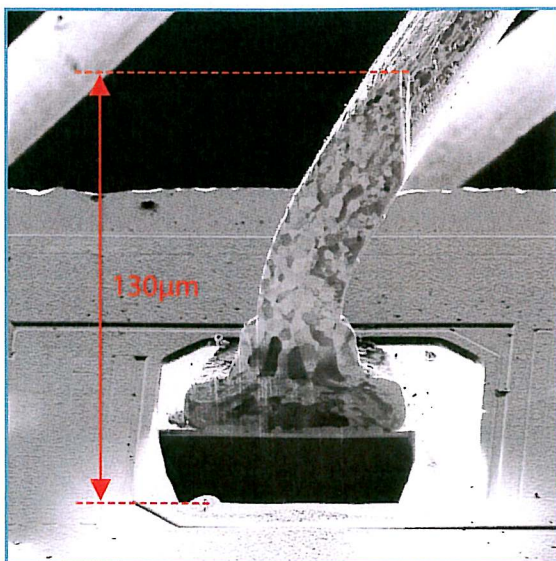
high resolution imaging and analysis and precision nanofabrication.

New low-damage fabrication techniques have been developed for materials sensitive to electron irradiation. Innovations in sample loading, sample navigation, and Micro-sampling increase analysis efficiency\*<sup>1</sup>.

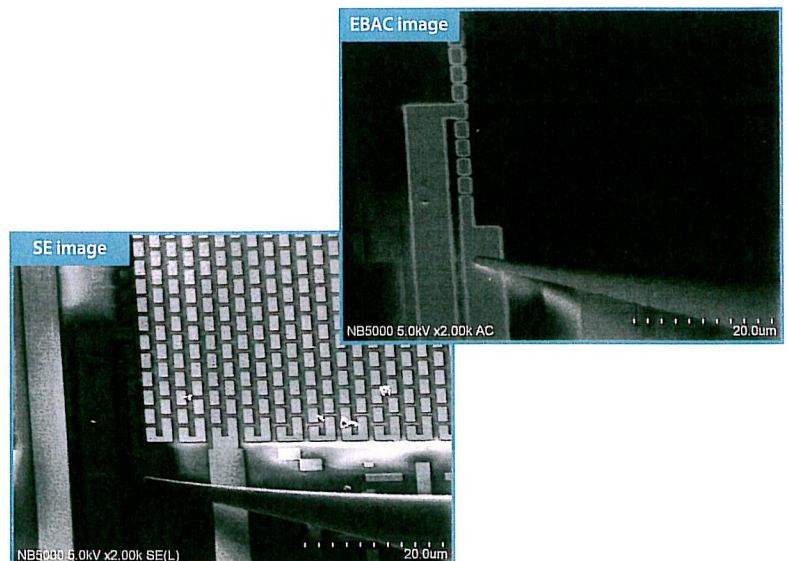


## Features

- Ultra-high performance FIB**  
 Low Cs FIB optics\*<sup>2</sup> deliver 50nA or more of beam current (@40kV) in an about 1 $\mu$ m spot-size. The high current enables unconventional large-area milling, hard material fabrication and high throughput multiple specimen preparation.
- New Micro-sampling\*<sup>2</sup>**  
 Hitachi's patented Micro-sampling technology provides smooth probe motion. Also, the probe can be used for newly developed absorbed current imaging\*<sup>1</sup> to aid fault isolation.
- High precision end-point detection**  
 High resolution SEM allows high precision end-point detection. Section-view function, which displays an outline of the cross-section utilizing the real-time FIB image, is ideal for preparing electron irradiation sensitive specimens like Low-K material.
- High resolution SEM**  
 Hitachi's unparalleled SEM column and detector design\*<sup>2</sup> enables high resolution SEM imaging during and after FIB fabrication.
- Holder compatibility with TEM/STEM\*<sup>1,2</sup>**  
 A side entry STEM/TEM-type stage\*<sup>1</sup> allows the use of the same specimen holder (compatible with NB5000 and Hitachi TEM/STEM). No tweezer handling of specimen during transfer results in higher throughput TEM/STEM analysis.



Large-area milling of wire bonding  
 (milled area : 75 (w)  $\times$  130 (h)  $\mu$ m, milling time : 19min.)



EBAC (Electron Beam Absorbed Current) imaging\*<sup>1</sup>  
 with new Micro-sampling system

\*<sup>1</sup> Optional accessory

\*<sup>2</sup> Hitachi patent Low Cs FIB optics : patent pending, Micro-sampling : JP2774884/U55270552, Section-view function : patent pending, SEM column and detector design : JP3081393,U55387793, Holder compatibility : JP2842083

## Specification

FIB	Accelerating voltage	1 ~ 40kV	
	Beam current	50 nA or more @40kV (CP)	
	SIM resolution	5nm @ 40kV (CP)	
	Magnification	x60 ~ x250,000	
	Ion source	Ga Liquid Metal Ion Source	
	Lens system	Low Cs 2-stage electrostatic lens system	
SEM	Accelerating voltage	0.5 ~ 30kV	
	SEM resolution	1.0 nm @ 15kV (CP) 2.1 nm @ 1kV (OWD)*2	
	Magnification	High Mag mode	x250 ~ x800,000
		Low Mag mode	x70 ~ x2,000
	Electron source	ZrO/W Schottky emission	
	Lens system	3-stage electromagnetic lens reduction system	
Signal selection	SEM	Upper SE, Lower SE, Absorbed current*1	
	FIB	Lower SE, Absorbed current*1	
Eucentric stage	Traverse range	X : 50mm (30mm*2), Y : 50mm (30mm*2), Z : 22mm T : -1.5 ~ 58.3°, R : 360°	
	Sample size	Maximum diameter	φ50mm (φ30mm*2)
Deposition	Material	Tungsten/Carbon (changeable)	
Micro-sampling	Probe exchange	Load lock type	
	Additional function	Touch sensing, Absorbed current imaging*1	

CP : Beam Cross Point  
OWD : Optimum Working Distance

\*1 Optional accessory  
\*2 When side entry stage is ordered

## Utilities

Temperature	15°C ~ 25°C (Variation during operation : 2°C or less/hr)
Humidity	60% RH or lower
Power	Single phase 200V (±10%), 8kVA (50/60Hz)
Grounding	D class, Grounding resistance : 100Ω or less Please use a water circulator.
Water	Flow rate : 1.0 ~ 1.3L/min (Water pressure : 50 ~ 130kPa) Water temperature : 10 ~ 20°C (Variation : 0.5°C or less/10 min.)
Gas	Air 0.4 ~ 0.6 MPa, For valve control N <sub>2</sub> gas 30 ~ 50kPa, Needed for N <sub>2</sub> gas column leak

## Optional accessories

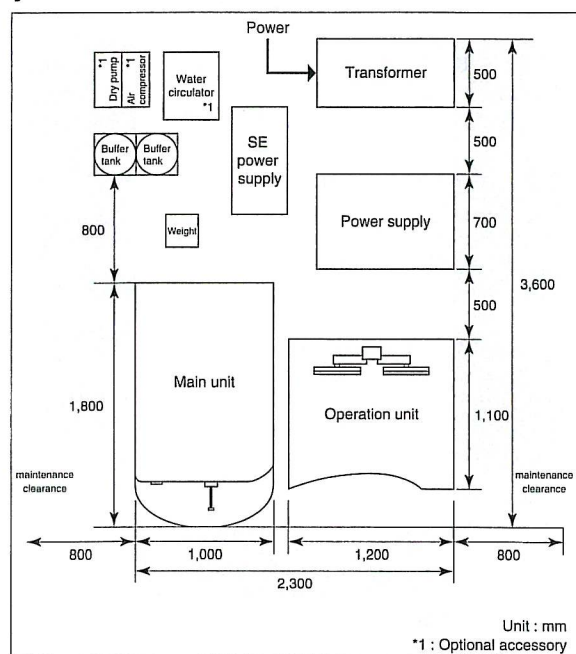
Holder scope, Absorbed current imaging, Automatic fabrication software, Side entry stage, Specimen rotation holder, Energy Dispersive X-ray spectrometer (EDX), Water circulator, Air compressor, Dry pump

## Dimensions and weight

Unit	Width x Depth x Height (mm)	Weight (kg)
Main unit	933 x 1,747 x 1,900	1,129
Operation unit	1,200 x 1,025 x 740	188
Power supply	980 x 640 x 1,565	463
Transformer	980 x 454 x 625	192
SE power supply	394 x 754 x 780	122
Buffer tank (x2)	@280 x 280 x 665	@18
Dry pump*1	400 x 252 x 336	25
Water circulator*1	450 x 400 x 660	55
Air compressor*1	400 x 230 x 550	18
Weight	200 x 180 x 160	40

\*1 Optional accessory

## Layout



NOTICE: For proper operation, follow the instruction manual when using the instrument.

Specifications in this catalog are subject to change with or without notice, as Hitachi High-Technologies Corporation continues to develop the latest technologies and products for our customers.

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